



General Information

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| Series | B45196P |
| Dielectric | MnO2 Tantalum |
| Style | SMD Chip |
| Description | SMD, Molded, High Temperature |
| Features | High Temperature, Automotive |
| RoHS | Yes |
| Termination | Tin |
| Qualifications | AEC-Q200 |
| AEC-Q200 | Yes |
| Notes | Obsolete. |

Dimensions

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| Footprint | 7343 |
| L | 7.3mm +/-0.3mm |
| W | 4.3mm +/-0.3mm |
| H | 4.1mm +/-0.3mm |
| S | 1.3mm +/-0.3mm |
| F | 2.4mm +/-0.1mm |
| K | 1.8mm TYP |

Packaging Specifications

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| Packaging | T&R, 330mm |
| Packaging Quantity | 4750 |

Specifications

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| Capacitance | 47 uF |
| Capacitance Tolerance | 20% |
| Voltage DC | 35 VDC (85C), 27.89 VDC (125C), 23.45 VDC (150C) |
| Temperature Range | -55/+150°C |
| Rated Temperature | 85°C |
| Dissipation Factor | 6% |
| Failure Rate | N/A |
| Resistance | 0.5 Ohms (100kHz) |
| Ripple Current | 574.5 mAmps (25C), 517.1 mAmps (85C), 229.8 mAmps (125C) |
| Leakage Current | 16.5 uA |